

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Original) An electronic device module comprising:
a wiring substrate having an insulating substrate with a porous structure including continuous pores and wiring conductors selectively formed in the porous structure; and
an electronic device directly connected to said wiring conductors formed in the porous structure.
2. (Currently Amended) The electronic device module according to claim 1, wherein said wiring conductors in the wiring substrate are grouped into a first wiring conductor extending in parallel with ~~[[a]]an~~ electronic device mounting surface of the porous insulating substrate and a second wiring conductor extending through the porous insulating substrate from its top surface to bottom surface.
3. (Original) The electronic device module according to claim 2, wherein said first wiring conductor is formed at a surface of said wiring substrate.
4. (Original) The electronic device module according to claim 2, wherein said first wiring conductor is embedded in said wiring substrate.

5. (Currently Amended) The electronic device module according to claim 2, wherein, in the junction of the first and second wiring conductors defined as planes in parallel with the electronic device mounting surface of the wiring substrate, the second wiring conductor along ~~[[the]]~~a longer extension of the first wiring conductor is ~~greater-~~wider than that along ~~[[the]]~~a shorter extension of the first wiring conductor.

6. (Original) The electronic device module according to claim 1, wherein the wiring substrate and the electronic device are directly connected with each other by bonding layers provided at contacts of the wiring conductors with terminal electrodes of the electronic device.

7. (Original) The electronic device module according to claim 1, wherein a size of the electronic device and a size of the wiring substrate are substantially the same.

8. (Original) The electronic device module according to claim 1, wherein a size of the electronic device is smaller than the size of the wiring substrate.

9. (Original) The electronic device module according to claim 1, wherein the insulating substrate has almost the same coefficient of thermal expansion as that of the electronic device.

10. (Currently Amended) The electronic device module according to claim 1, wherein the electronic device is ~~[[of]]~~a semiconductor chip, and the wiring substrate serves as a package base on which the semiconductor chip is mounted.

11. (Currently Amended) The electronic device module according to claim 10, wherein the semiconductor chip ~~[[that]]~~ is mounted on a top surface of the package base, with its terminal electrodes facing downwards, ~~[[and]]~~ a part of the wiring conductors of the package base are directly coupled to the semiconductor chip, and other part of the wiring conductors extend to a bottom side of the package base.

12. (Currently Amended) The electronic device module according to claim 10, wherein the electronic device is ~~[[of]]~~a semiconductor chip that is mounted on a bottom surface of the package base, with its terminal electrodes facing upwards, ~~[[and]]~~ a part of the wiring conductors of the package base are directly coupled to the semiconductor chip, and other part of the wiring conductors extend at the bottom surface of the package base.

13. (Withdrawn) A manufacturing method of an electronic device module comprising:

mounting an electronic device on a surface of an insulating substrate having a porous structure including continuous pores and including photosensitive material which produces or vanishes ion exchange groups upon exposure to energy rays using a mask;

exposing the energy rays to change the photosensitive material; and
performing electroless plating to form wiring conductors in continuous pores
generated by the change of the photosensitive material.

14. (Withdrawn) The method according to claim 13, further comprising
impregnating plastic material into the porous insulating substrate.

15. (Withdrawn) The method according to claim 13, wherein said mask has a
light shielding pattern which completely shields the ray, a partial transmitting pattern
which partially transmits the ray and a through pattern which transmits the ray without
attenuation.

16. (Withdrawn) The method according to claim 15, wherein said exposure is
performed, if necessary, for the partial transmitting pattern, to converge the ray in the
internal of the porous insulating substrate using a lens.